

ASM International Highlights Advances in Transistor Manufacturing Technology at Luncheon Seminar

Bilthoven, the Netherlands, December 06, 2007 – ASM International N.V. (NASDAQ: ASMI and Euronext Amsterdam: ASM) today announced that it will be hosting a technical luncheon seminar in Washington D.C. on Wednesday, December 12, 2007, the last day of the International Electron Devices Meeting (IEDM). The seminar will highlight ASM's leading-edge transistor manufacturing technologies that provide power and speed advantages on chips in high volume manufacturing, including Atomic Layer Deposition (ALD) of high-k gates, and Selective Epitaxial Growth (SEG) of strained materials for PMOS and NMOS transistors.

The event will be presented in two parts:

Part 1) 11:30 to 12:15: Walk-in Poster Session and Lunch Buffet. Topics include SEG of Silicon Germanium (SiGe) and Silicon-Carbon (SiC), high-k deposition, and silicidation for high volume manufacturing and their extendability for 32nm, 22 nm and smaller devices

Part 2) 12:15 to 13:20: Presentations by Industry Leaders on Key Topics in Transistor Engineering

- Frank Yang (AMD) on “Materials Interactions and Integration Challenges for High-Performance Silicon-Based MOSFET's Using Embedded Source/Drain Stressors”
- Philippe Absil (IMEC) on “Engineering Low-Vt CMOS High-k Gate Stacks using ALD Cap Layers”

Following the presentations, there will be an opportunity for continued dialogue around posters and presentation topics.

The ASM seminar will take place in the Kalorama room at The Churchill Hotel, 1914 Connecticut Ave., Washington, D.C (across from the Hilton Washington). The room will open at 11:30 am. Interested parties should contact Rosanne de Vries, +31 (0)30- 2298569, rosanne.de.vries@asm.com.

About ASM International

ASM International N.V., headquartered in Bilthoven, the Netherlands, and its subsidiaries design and manufacture equipment and materials used to produce semiconductor devices. ASM International and its subsidiaries provide production solutions for wafer processing (Front-end segment) as well as assembly and packaging (Back-end segment) through facilities in the United States, Europe, Japan and Asia. ASM International's common stock trades on NASDAQ (symbol ASMI) and the Euronext Amsterdam Stock Exchange (symbol ASM). For more information, visit ASMI's website at www.asm.com.

Safe Harbor Statement under the U.S. Private Securities Litigation Reform Act of 1995: All matters discussed in this statement, except for any historical data, are forward-looking statements. Forward-looking statements involve risks and uncertainties that could cause actual results to differ materially from those in the forward-looking statements. These include, but are not limited to, economic conditions and trends in the semiconductor industry generally and the timing of the industry cycles specifically, currency fluctuations, the timing of significant orders, market acceptance of new products, competitive factors, litigation involving intellectual property, shareholder and other issues, commercial and economic disruption due to natural disasters, terrorist activity, armed conflict or political instability, epidemics and other risks indicated in the Company's filings from time to time with the U.S. Securities and Exchange Commission, including, but not limited to, the Company's reports on Form 20-F and Form 6-K. The Company assumes no obligation nor intends to update or revise any forward-looking statements to reflect future developments or circumstances.

Media Contacts:

Mary Jo Dieckhaus: +1 212 986 2900, maryjo.dieckhaus@asm.com

Ivo Raaijmakers: + 31 30 229 8587, ivo.raaijmakers@asm.com